CLAIMS

[Claim 1] A method for treating a substrate after etching, comprising:

cleaning a substrate to be treated with a basic cleaning composition that contains a basic compound and water and has a pH of 10 or more,

wherein the substrate to be treated has a metal layer containing a Group 6 element metal and has been etched with an etchant containing phosphoric acid, nitric acid, water, and an organic amine.

[Claim 2] The method according to claim 1, comprising washing the substrate to be treated with water before the cleaning process.

[Claim 3] The method according to claim 1 or 2, wherein a temperature of the cleaning composition in the cleaning process is 0°C or more and 100°C or less.

[Claim 4] The method according to any one of claims 1 to 3, wherein a cleaning time in the cleaning process is 10 seconds or more and 120 minutes or less.

[Claim 5] The method according to any one of claims 1 to 4, wherein a temperature (etching temperature) of the etchant in the etching is 0°C or more and 100°C or less.

[Claim 6] The method according to any one of claims 1 to 5, wherein an etching time in the etching is 1 minute or more and 180 minutes or less.

[Claim 7] The method according to any one of claims 1 to 6, wherein the basic compound of the basic cleaning composition includes at least one selected from the group consisting of ammonia, an alkali metal hydroxide, and an organic amine or a salt thereof.

[Claim 8] The method according to any one of claims 1 to 7, wherein the Group 6 element metal is at least one selected from the group consisting of chromium (Cr), molybdenum (Mo), tungsten (W), and seaborgium (Sg).

[Claim 9] The method according to any one of claims 1 to 8, wherein the acid contained in the etchant is acid containing phosphoric acid and nitric acid.

[Claim 10] The method according to any one of claims 1 to 9, wherein an organic amine compound contained in the etchant is at least one organic amine compound selected from the group consisting of polyalkyleneimine, a polymer having a constitutional unit derived from diallylamine, polyalkylene polyamine, alkylamine, alkanolamine, alicyclic amine, aromatic amine, and amino acid.

[Claim 11] The method according to any one of claims 1 to 10, wherein the basic cleaning composition has a pH of 11 or more.

[Claim 12] The method according to any one of claims 1 to 11, wherein the basic cleaning composition has a pH of 10 or more and 14 or less.